



## End of life for M60A NAND in QDP TSOP Package

PCN: 33292

Published: 2019-06-25

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<b>Type:</b>	End of Life
<b>Description:</b>	Micron will end of life the M60A NAND in QDP TSOP package. This document supersedes the original PCN 32828.  Refer to <a href="http://www.Micron.com">www.Micron.com</a> for the replacement part datasheet.
<b>Reason:</b>	Change in Market Demand
<b>Product Affected:</b>	M60A NAND in QDP TSOP package

Affected Micron Part Number Component	Recommended Replacement	Customer Part Number
<b>MT29F16G08AJADAWP-IT:D</b>	<b>MT29F16G08ABACAWP-ITZ:C</b>	<b>557-1838-2-ND</b>

\*Materials that have been ordered are in **bold**.

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<b>Method of Identification:</b>	Marketing Part Number
<b>Micron Sites Affected:</b>	All Sites
<b>Last Purchase Date*:</b>	2019-12-25
<b>Last Shipment Date:</b>	2020-06-25

\*Early placement of orders is encouraged as an increase in demand for this product could potentially exceed Micron's ability to meet all requests. All products from a previously accepted order that have not shipped as of the last-time purchase date will be considered non-cancelable. Should additional supply be available after the last-time purchase date, Micron may accept orders for product and such orders placed will be considered non-cancelable.

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

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## Attachments

There are no attachments on this PCN